

Application No. 10/643,043

Docket No. DP-308286

Amendment dated October 20, 2005

Reply to Advisory Action of October 3, 2005

**Amendments to the Specification:**

Please replace paragraph [0011] with the following amended paragraph:

**[0011]** Figure 2 is a cross-sectional view of a non-overmolded package containing flip chip ~~a flip chip~~ devices mounted to a substrate, with a heat-conductive member contacting the topside of each device.